

REMARKS

Claims 1-22 are pending. The specification has been amended at paragraph 0001, to show that the parent application 09/907,485 has issued as U.S. Patent No. 6,691,720. A new Declaration is enclosed responsive to paragraph 1 of the September 9, 2004 Office Action.

Claims 7, 15, and 21 have been amended in view of the objections at paragraphs 3-5 of the September 9, 2004, Office Action. Claim 19 has been amended to delete "above the process liquid," at line 6. The content of new dependent claim 22 is at paragraph 0028.

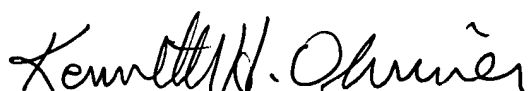
A Terminal Disclaimer disclaiming over U.S. Patent No. 6,427,359 is enclosed. Accordingly, the grounds for rejection of claims 1-6, 9-15, and 18-21 at paragraph 7 of the September 9, 2004, Office Action are removed. Similarly, the enclosed Terminal Disclaimer removes claims 18-26 of U.S. Patent No. 6,427,359 from the combination relied on in rejecting claims 7-8 and 15-17, in paragraph 8 of the Office Action. The remaining reference, U.S. Patent No. 5,221,360 to Thompson et al., by itself, does not disclose various elements of claims 7-8 and 15-17. These claims are therefore now also believed to be in condition for allowance.

In view of the foregoing, it is submitted that the claims are in condition for allowance. A Notice of Allowance is therefore requested.

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REPLACEMENT SPECIFICATION SHEET:

[0001] This Application is a Division of U.S. Patent Application Serial No. 09/907,485, filed on July 16, 2001, and now ~~pending~~ U.S. Patent No. 6,691,720, and is incorporated herein by reference.

COMPLETE SET OF PENDING CLAIMS:

1. [Original] A method for processing a workpiece, comprising the steps of:

placing the workpiece into a workpiece support;

enclosing the workpiece support holding the workpiece within a process chamber;

providing a process liquid into the process chamber; and

pivoting the process chamber to remove process liquid from the process chamber.

2. [Original] The method of claim 1 where the workpiece is at least partially immersed in the process liquid.

3. [Original] The method of claim 1 further comprising the step of rotating the workpiece support.

4. [Original] The method of claim 1 further comprising the step of introducing a process gas or vapor into the process chamber.

5. [Original] The method of claim 1 further comprising the step of enclosing the process chamber within an outer containment chamber.

6. [Original] The method of claim 1 where the process chamber is pivoted at a controlled rate to remove liquid from the process chamber.

7. [Currently Amended] The method of claim 1 further comprising the step of drawing off a surface layer of the liquid within the ~~[inner]~~ process chamber via vacuum.

8. [Original] The method of claim 7 where the gas comprises nitrogen, air, argon or HF.

9. [Original] The method of claim 1 further comprising the step of providing sonic energy to the workpiece.

10. [Original] The method of claim 5 further comprising the step of sealing the process chamber with a process chamber door.

11. [Original] The method of claim 1 further comprising the steps of introducing a rinsing liquid into the process chamber, and then introducing a drying gas and an organic vapor into the process chamber, to facilitate removal of the rinsing liquid from the workpiece.

12. [Original] The method of claim 3 further comprising the step of rotating the workpiece support while the workpiece support is at least partially immersed in the process liquid.

13. [Original] The method of claim 1 further comprising the step of pivoting the process chamber from a first position, where the process chamber holds the process liquid at a level at least partially immersing the workpiece held in the workpiece holder, to a second position where liquid within the process chamber drains out, through a drain opening in the process chamber.

14. [Original] The method of claim 1 further comprising the step of spraying process liquid onto the workpiece.

15. [Currently Amended] The method of claim 1 further comprising the step of extending the workpiece support out of the process chamber, for loading and unloading a workpiece[s], and moving the workpiece support into the process chamber, for processing a workpiece[s].

16. [Original] The method of claim 1 wherein the process chamber has cylindrical sidewalls, further including the step of pivoting the process chamber about an axis parallel to the cylindrical sidewalls.

17. [Original] The method of claim 1 further comprising the step of holding the workpiece in an upright vertical position in the workpiece support.

18. [Original] The method of claim 1 further comprising the step of drying the workpiece by introducing a vapor of an organic solvent into the process chamber above the process liquid.

19. [Currently Amended] A method for processing a batch of wafers, comprising the steps of:

placing the batch of wafers onto a holder, with the wafers spaced apart from each other and in a generally vertical upright position;

containing the batch of wafers and the holder within a process chamber;

introducing a process liquid into the process chamber;

introducing a gas or vapor into the process chamber~~[-above the process liquid];~~ and

pivoting the process chamber at a controlled rate, to maintain a drain opening in the process chamber at a position where process liquid drains out of the chamber through the drain opening.

20. [Original] The method of claim 19 further comprising the step of spinning the wafers and the holder within the process chamber, after draining at least some of the liquid out of the process chamber.

21. [Currently Amended] A method for processing a workpiece, comprising the steps of:

placing the workpiece into a workpiece support;
enclosing the workpiece support holding the workpiece into a chamber;
rotating the [first] chamber about the workpiece support; and
providing a process fluid into the [first] chamber from at least one fluid
supply opening on the [first] chamber.

22. [New] The method of claim 19 wherein the gas or vapor is
introduced into the chamber via a manifold positioned below the wafers.